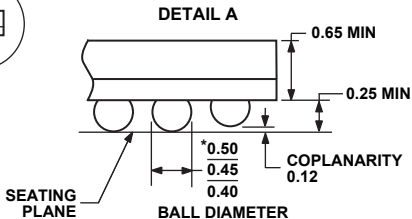
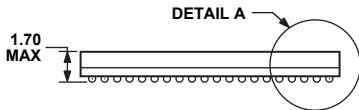
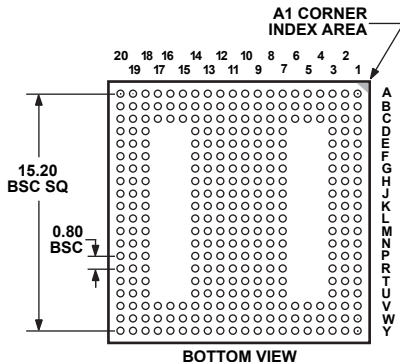
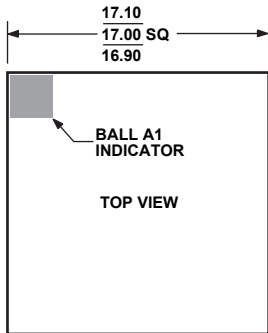


316-Ball Chip Scale Package Ball Grid Array [CSP_BGA]

(BC-316)

Dimensions shown in millimeters

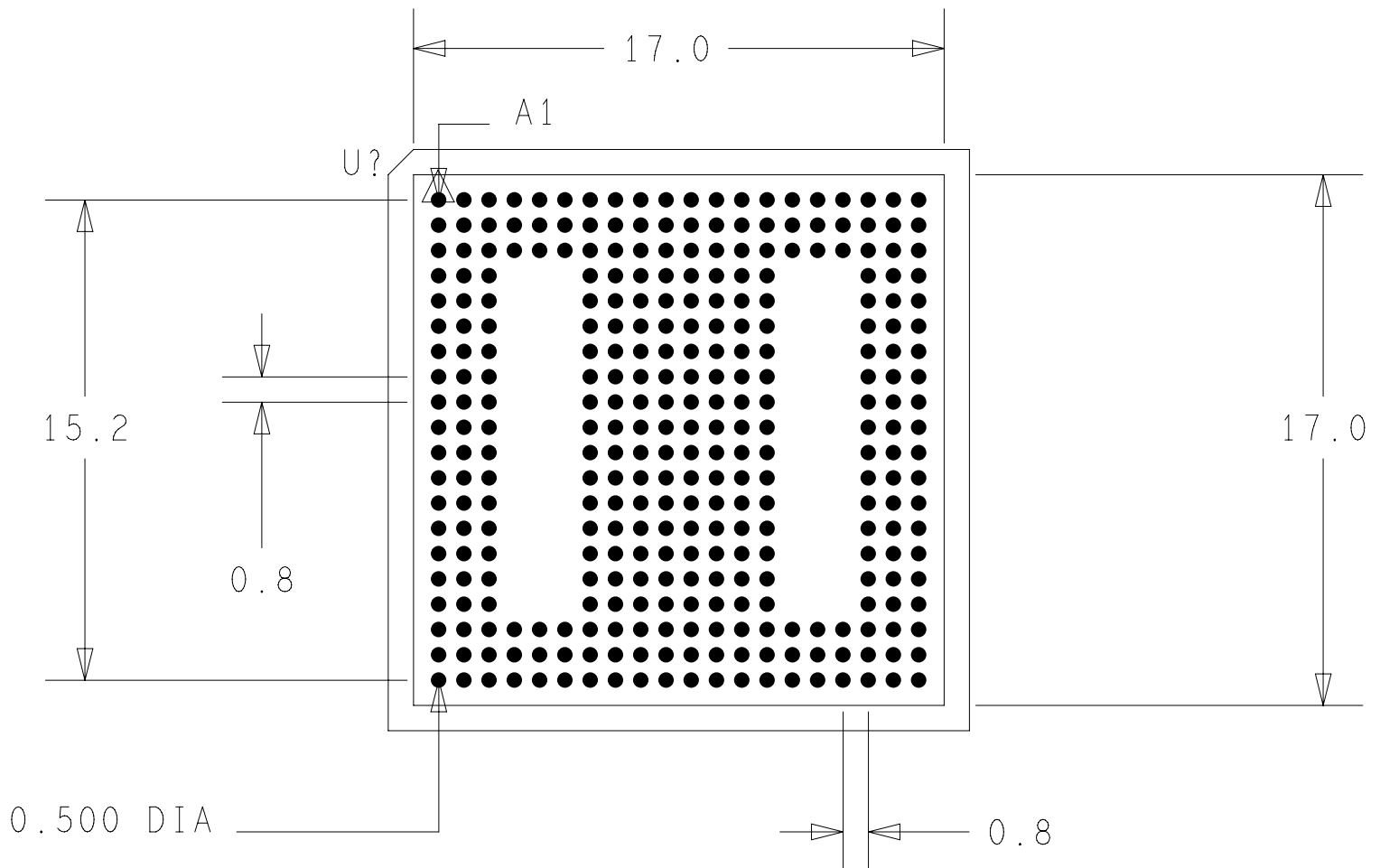


*COMPLIANT TO JEDEC STANDARDS MO-205-AM
WITH EXCEPTION TO BALL DIAMETER.

Analog Devices

BC-316

REV A



(Dim. are in MM)

LAST MODIFIED 09/17/07